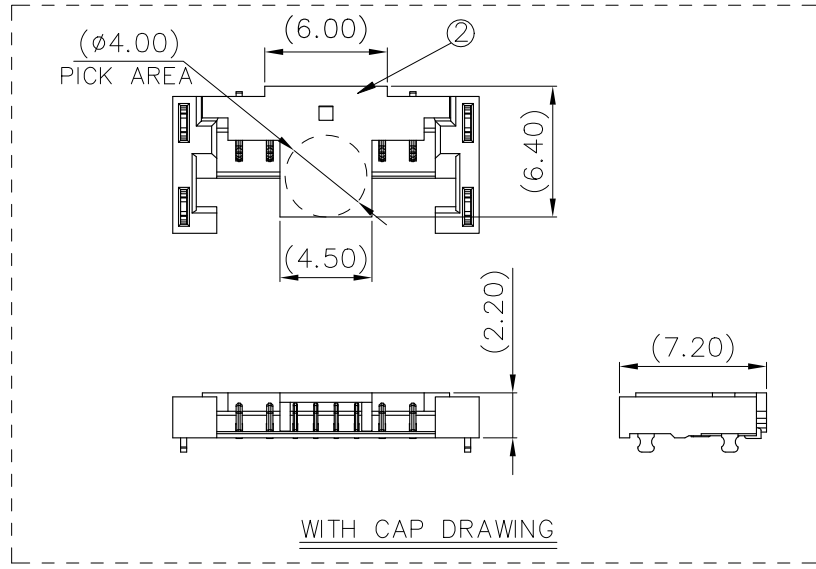
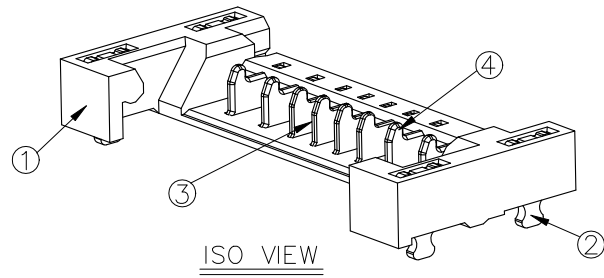
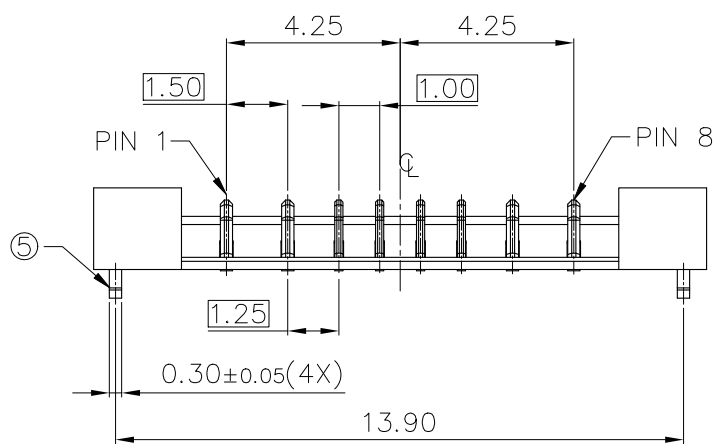
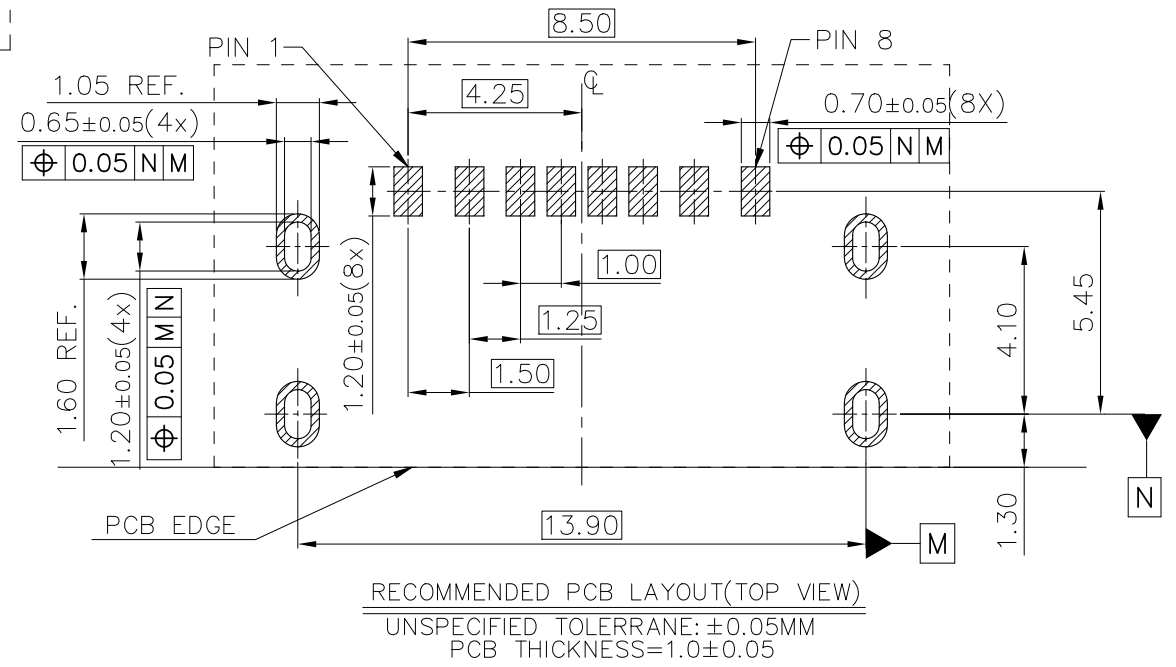
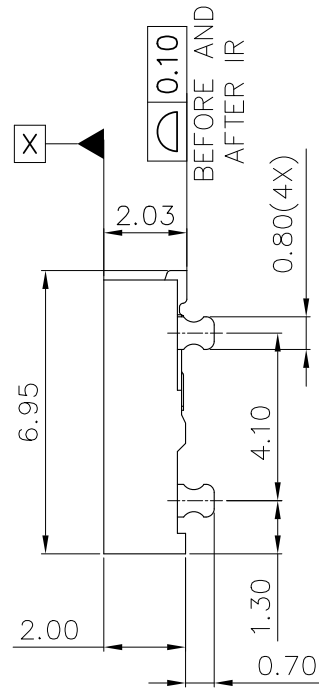
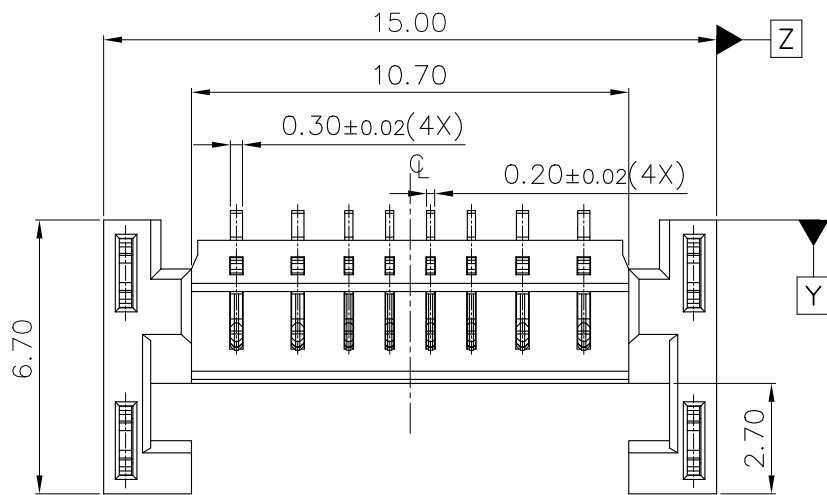
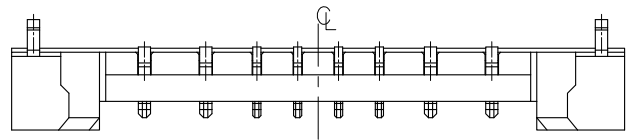




REV.	ECN. NO.	APPD.
A	ECN180910007	Darren Lei
B	ECN190816013	River Yao
Bx1	SWR-RD1020201012001	Mike Wu
Bx2	SWR-RD1020201016005	Mike Wu



- NOTES:
- 1.DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5M-1994.
  - 2.ELECTRICAL CHARACTERISTICS:
    - 2-1. CONTACT CURRENT RATING: POWER CONTACT: 4.8A PER PIN MAX  
SIGNAL CONTACT: 1.8A PER PIN MAX
    - 2-2. LOW LEVEL CONTACT RESISTANCE:  
POWER CONTACT: 20 mΩ MAX INITIAL, 40 mΩ MAX AFTER TEST  
SIGNAL CONTACT: 15 mΩ MAX INITIAL, 30 mΩ MAX AFTER TEST
    - 2-3. INSULATION RESISTANCE: 100MOHMS MIN. AT 100VDC.
    - 2-4. DIELECTRIC WITHSTANDING VOLTAGE: 250V RMS AT 60Hz FOR 1 MINUTE.
  - 3.MECHANICAL CHARACTERISTICS:
    - 3-1.INSERTION FORCE: 20N MAX.
    - 3-2.UNMATING FORCE: 4N MIN.
    - 3-3.DURABILITY: 30 MATING CYCLES.
  - 4.OPERATING TEMPERATURE : -40°C TO 85°C.
  - 5.HARMFUL MATERIAL CONTROL SHOULD MEET DOCUMENT "DQSP2014".



PART NO.  
WS5208\*-S0201-1H

WTB CONN. HALOGEN FERR&LEAD FREE

PITCH 5: 1.50mm PROFILE HEIGHT 20: 2.00mm

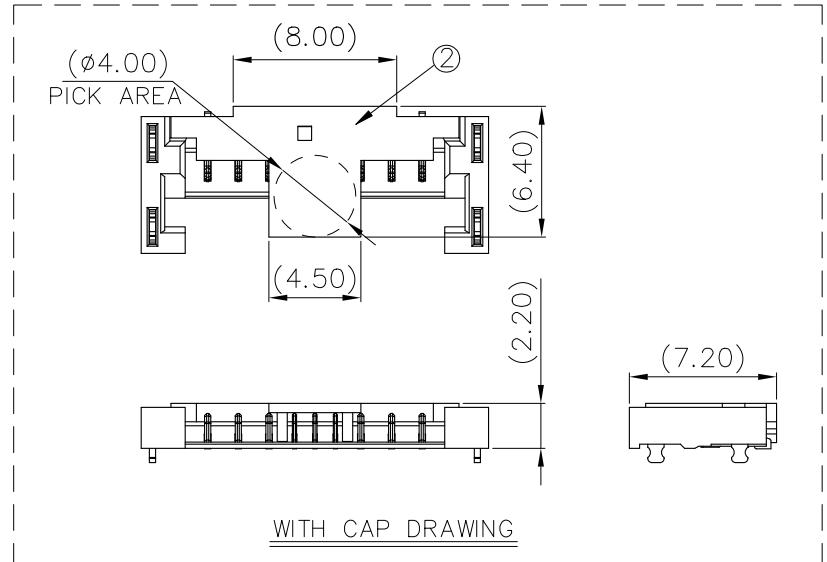
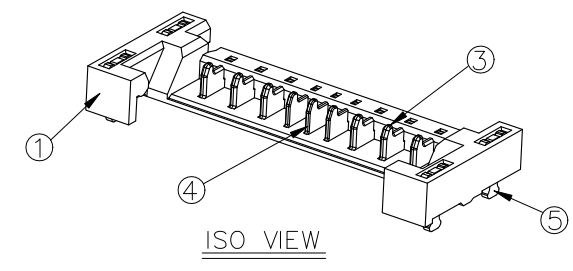
POS. NO. 08=8POS. CONTACT AREA PLATING  
0: MATTE TIN PLATING  
2: MATTE TIN PLATING&HIGH TERMINAL  
5: 5u" MIN GOLD PLATING

⑤	PAD	4	METAL ALLOY	50u" Min NICKEL UNDERPLATED OVER ALL. 100u" Min. MATTE TIN PLATED OVER ALL.
④	SIGNAL PIN	4	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA, 50u" Min NICKEL UNDERPLATED OVER ALL. 100u" Min. MATTE TIN PLATED OVER ALL.
③	POWER PIN	4	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL.
②	ACTUATOR	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK
①	HOUSING	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK

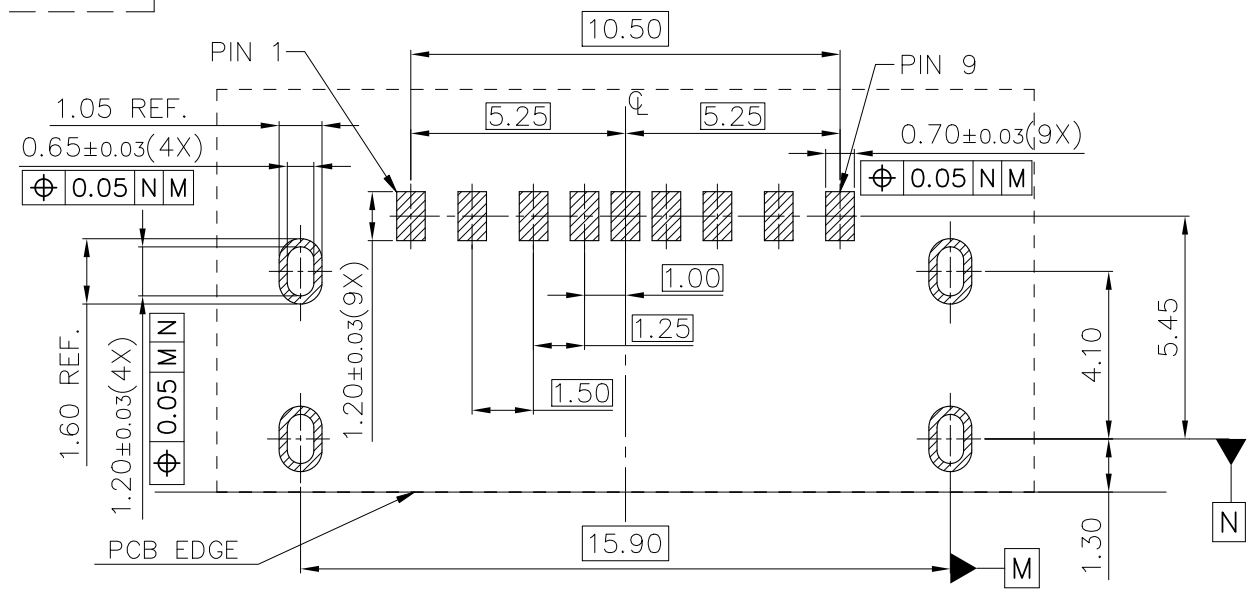
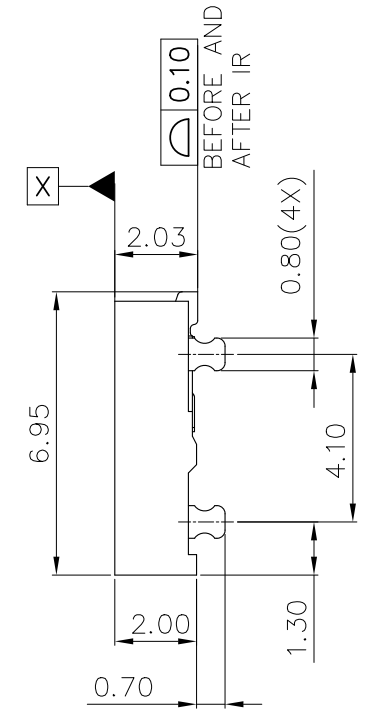
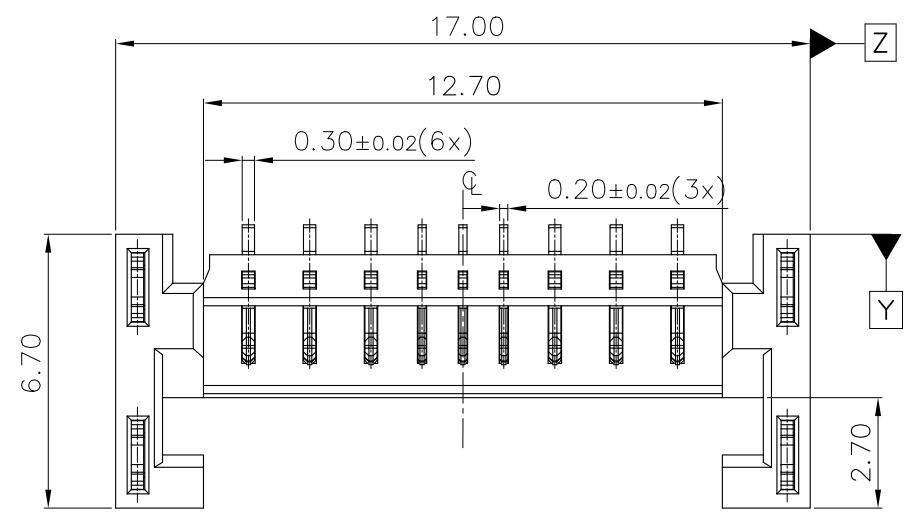
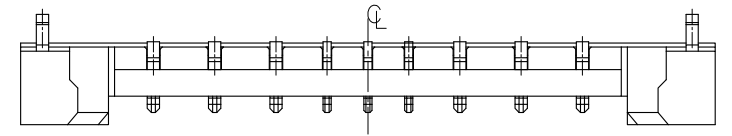
ITEM NO.	NAME	Q'TY	MATERAIL	FINISH
UNITS: mm		GENERAL TOLERANCE		APPROVED: Mike Wu
DATE: 10/16'20		X. ±0.30	X.* ±3°	CHECKED: Wes Wu
SCALE: N/A		.X ±0.20	.X* ±2°	DRAWING: Ruiju YOU
SHEET: 1/4		MATERIAL: SEE TABLE	Q'TY N/A	PART NO.(INTENDED USE) WS52***-S0201-1H
REV.: Bx2		FINISH: SEE TABLE		TITLE: CUSTOMER DRAWING FOR 1.00&1.50mm PITCH 2.00mmH CABLE SIDE WTB CONN.
				DRAWING NO.: 820-0000-0725

REV.	ECN. NO.	APPD.

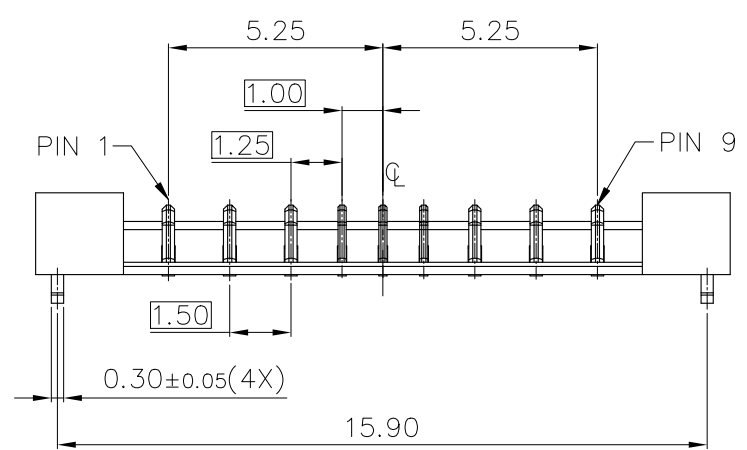
RoHS HF



- NOTES:
- 1.DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5M-1994.
  - 2.ELECTRICAL CHARACTERISTICS:
    - 2-1. CONTACT CURRENT RATING: POWER CONTACT: 4.0A PER PIN MAX  
SIGNAL CONTACT: 2.0A PER PIN MAX
    - 2-2. LOW LEVEL CONTACT RESISTANCE:  
POWER CONTACT: 20 mΩ MAX INITIAL. 40 mΩ MAX AFTER TEST  
SIGNAL CONTACT: 15 mΩ MAX INITIAL. 30 mΩ MAX AFTER TEST
    - 2-3. INSULATION RESISTANCE: 100MOHMS MIN. AT 100VDC.
    - 2-4. DIELECTRIC WITHSTANDING VOLTAGE: 250V RMS AT 60Hz FOR 1 MINUTE.
  - 3.MECHANICAL CHARACTERISTICS:
    - 3-1.INSERTION FORCE: 20N MAX.
    - 3-2.UNMATING FORCE: 4N MIN.
    - 3-3.DURABILITY: 30 MATING CYCLES.
  - 4.OPERATING TEMPERATURE : -40°C TO 85°C.
  - 5.HARMFUL MATERIAL CONTROL SHOULD MEET DOCUMENT "DQSP2014".



RECOMMENDED PCB LAYOUT(TOP VIEW)  
UNSPECIFIED TOLERRANE: ±0.05MM  
PCB THICKNESS=1.0±0.05



PART NO.  
WS5209\*-S0201-1H

WTB CONN.      HALOGEN FERR&LEAD FREE

PITCH 5: 1.50mm      PROFILE HEIGHT 20: 2.00mm

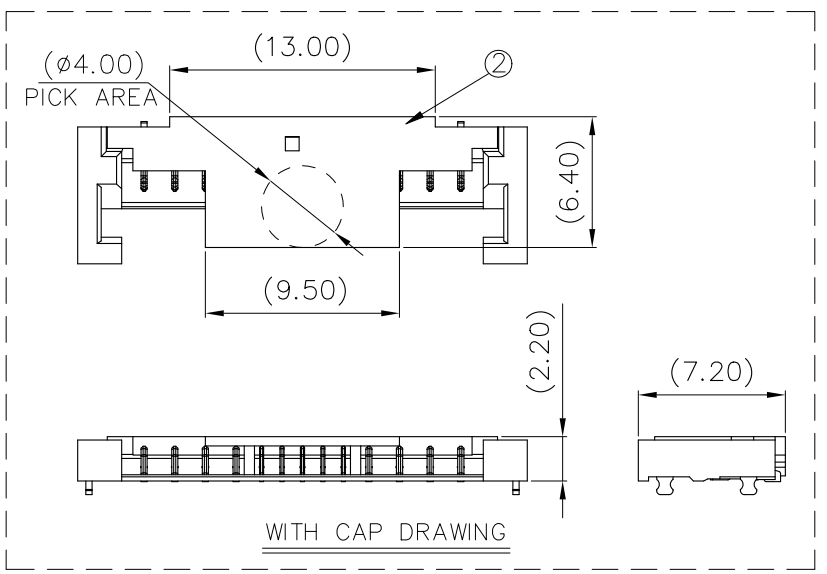
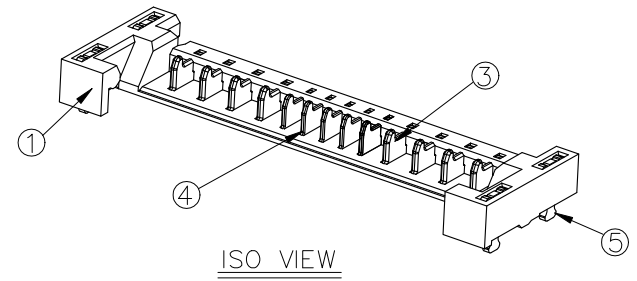
POS. NO. 09=9POS.      CONTACT AREA PLATING  
0: MATTE TIN PLATING  
2: MATTE TIN PLATING&HIGH TERMINAL  
5: 5u" MIN GOLD PLATING

⑤	PAD	4	METAL ALLOY	50u" Min NICKEL UNDERPLATED OVER ALL. 100u" Min. MATTE TIN PLATED OVER ALL.
④	SIGNAL PIN	3	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA, 50u" Min NICKEL UNDERPLATED OVER ALL. 100u" Min. MATTE TIN PLATED OVER ALL.
③	POWER PIN	6	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL.
②	ACTUATOR	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK
①	HOUSING	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK
ITEM NO.	NAME	Q'TY	MATERAIL	FINISH

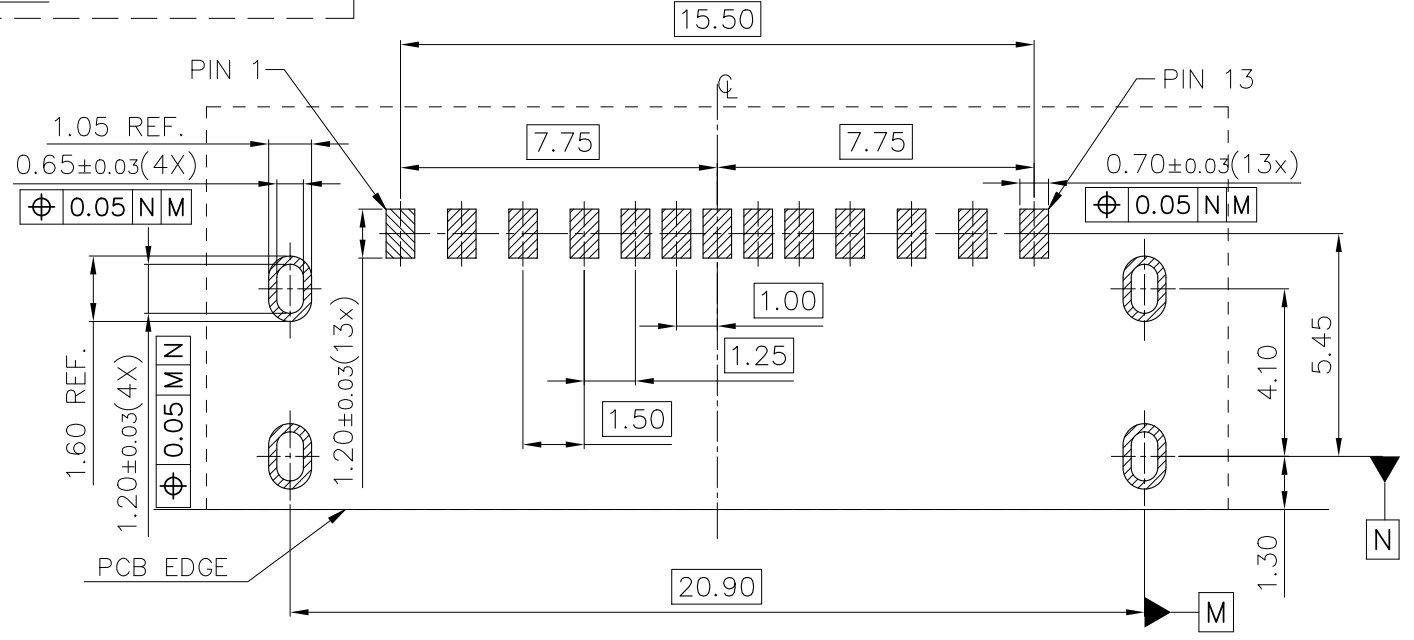
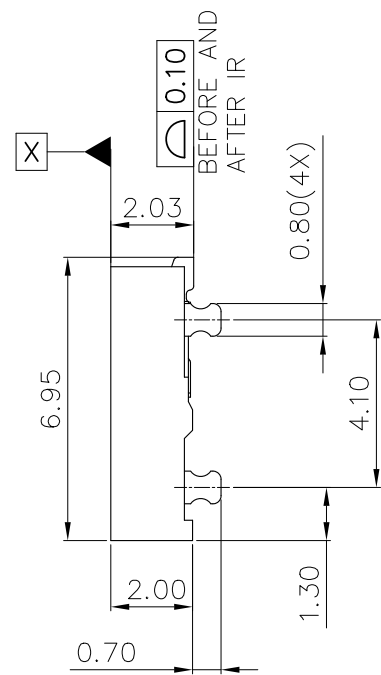
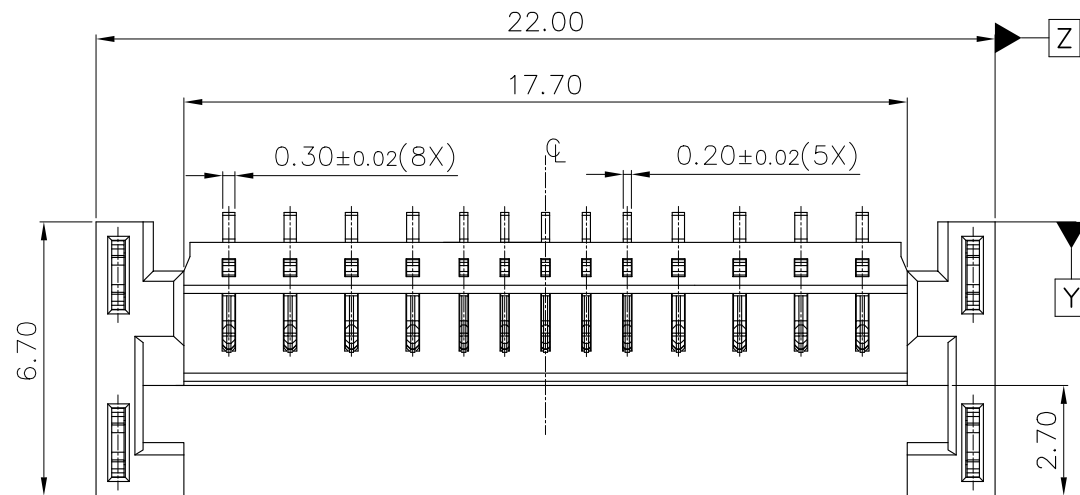
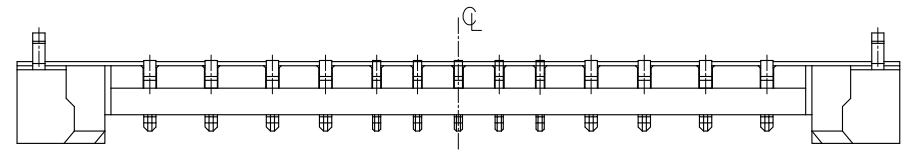
UNITS: mm	GENERAL TOLERANCE		APPROVED: Mike Wu	PART NO.(INTENDED USE) WS52**0-S0201-1H
DATE: 10/16'20	X. ±0.30	X.* ±3°	CHECKED: Wes Wu	TITLE: CUSTOMER DRAWING FOR 1.00&1.50mm PITCH 2.00mmH CABLE SIDE WTB CONN.
SCALE: N/A	.X ±0.20	.X* ±2°	DRAWING: Ruiju YOU	DRAWING NO.: 820-0000-0725
SHEET: 2/4	MATERIAL: SEE TABLE	Q'TY N/A	<b>Drapho ELECTRONICS TECHNOLOGY CO., LTD</b>	
REV.: Bx2	FINISH: SEE TABLE			

REV.	ECN. NO.	APPD.

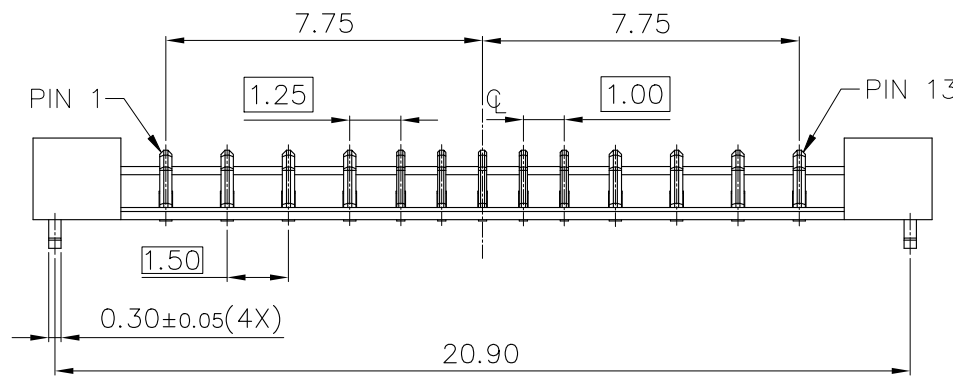
**RoHS** **HF**



- NOTES:
- DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5M-1994.
  - ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: POWER CONTACT: 4.0A PER PIN MAX  
SIGNAL CONTACT: 2.0A PER PIN MAX
    - LOW LEVEL CONTACT RESISTANCE:  
POWER CONTACT: 20 mΩ MAX INITIAL. 40 mΩ MAX AFTER TEST  
SIGNAL CONTACT: 15 mΩ MAX INITIAL. 30 mΩ MAX AFTER TEST
    - INSULATION RESISTANCE: 100MOHMS MIN. AT 100VDC.
    - DIELECTRIC WITHSTANDING VOLTAGE: 250V RMS AT 60Hz FOR 1 MINUTE.
  - MECHANICAL CHARACTERISTICS:
    - INSERTION FORCE: 30N MAX.
    - UNMATING FORCE: 4N MIN.
    - DURABILITY: 30 MATING CYCLES.
  - OPERATING TEMPERATURE : -40°C TO 85°C.
  - HARMFUL MATERIAL CONTROL SHOULD MEET DOCUMENT "DQSP2014".



RECOMMENDED PCB LAYOUT(TOP VIEW)  
UNSPECIFIED TOLLERRANE: ±0.05MM  
PCB THICKNESS=1.0±0.05



PART NO.  
WS5213\*-S0201-1H

- WTB CONN.
- PITCH 5: 1.50mm
- POS. NO. 13=13POS.
- HALOGEN FERR&LEAD FREE
- PROFILE HEIGHT 20: 2.00mm
- CONTACT AREA PLATING 0: MATTE TIN PLATING 2: MATTE TIN PLATING&HIGH TERMINAL 5: 5u" MIN GOLD PLATING

⑤	PAD	4	METAL ALLOY	50u" Min NICKEL UNDERPLATED OVER ALL. 100u" Min. MATTE TIN PLATED OVER ALL.
④	SIGNAL PIN	5	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA, 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL.
③	POWER PIN	8	COPPER ALLOY	5u"MIN GOLD PLATED ON CONTACT AREA GOLD FLASH ON SOLDER AREA 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL. 50u" Min NICKEL UNDERPLATED OVER ALL.
②	ACTUATOR	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK
①	HOUSING	1	HIGHTEMP-PLASTIC	UL94V-0,BLACK
ITEM NO.	NAME	Q'TY	MATERAIL	FINISH

UNITS: mm	GENERAL TOLERANCE		APPROVED: Mike Wu	PART NO.(INTENDED USE) WS52**0-S0201-1H
DATE: 10/16'20	X. ±0.30	X.* ±3°	CHECKED: Wes Wu	TITLE: CUSTOMER DRAWING FOR 1.00&1.50mm PITCH 2.00mmH CABLE SIDE WTB CONN.
SCALE: N/A	.X ±0.20	.X* ±2°	DRAWING: Ruiju YOU	DRAWING NO.: 820-0000-0725
SHEET: 3/4	MATERIAL: SEE TABLE	Q'TY N/A	<b>Drapho ELECTRONICS TECHNOLOGY CO., LTD</b>	
REV.: Bx2	FINISH: SEE TABLE			

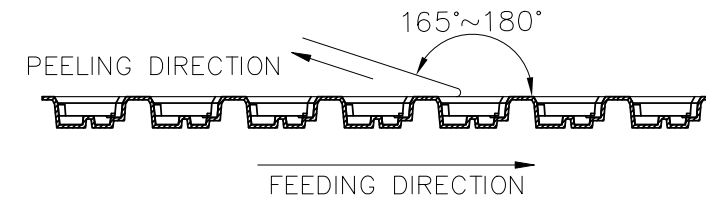
AUTO CAD GENERATED DRAWING, DON'T CHANGE BY HAND.

**RoHS** **HF**

REV.	ECN. NO.	APPD.

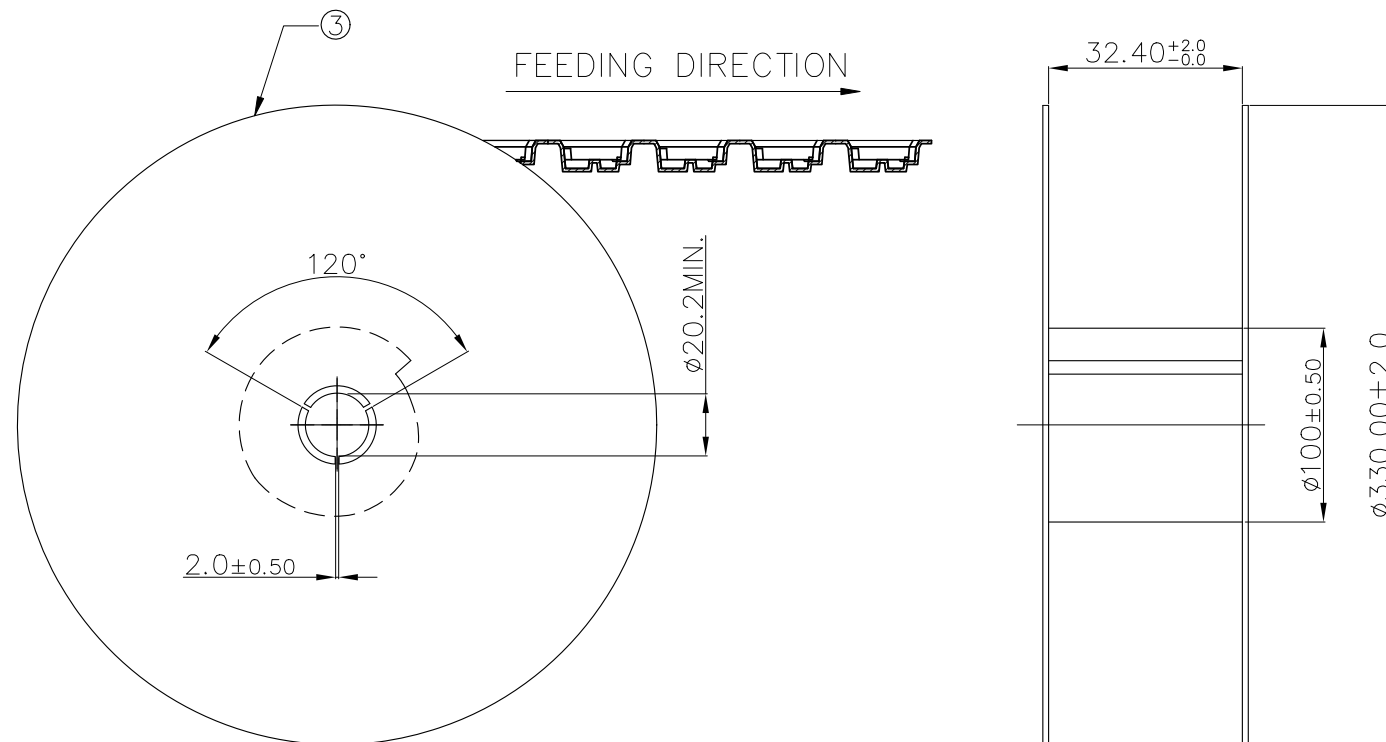
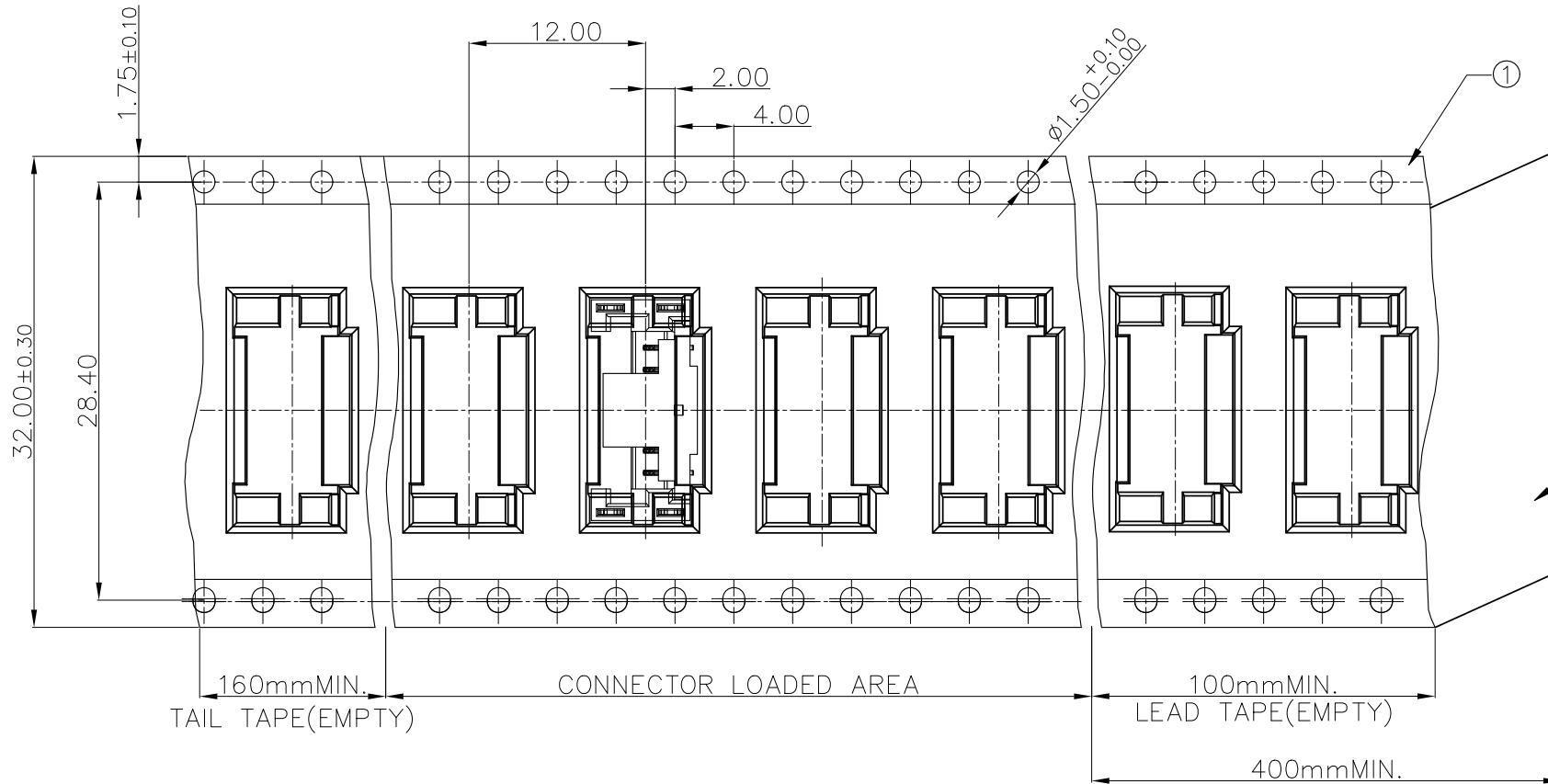
NOTES:

- 1.10 PITCHES CUMULATIVES TOLERANCE ON TAPE IS +/-0.20mm;
- 2.COVER TAPE PEELING STRENGTH :0.13Kgf MAX. AT 300mm/MINUTE;



3.PACKAGING CAPACITY:

P/N	PCS/REEL	REEL/BOX	PCS/BOX
WS5208*-S0201-1H	1500	6	9000
WS5209*-S0201-1H	1500	6	9000
WS5213*-S0201-1H	1500	6	9000



③	REEL	POLYSTYRENE
②	COVER TAPE	POLYSTER
①	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

UNITS: mm	GENERAL TOLERANCE		APPROVED: Mike Wu	PART NO.(INTENDED USE) WS52**0-S0201-1H
DATE: 10/16'20	X. :±0.30 .X :±0.20 .XX :±0.15	X.* :±2° .X.* :±1° .XX.* :±0.15 .XXX.*	CHECKED: Wes Wu	TITLE: CUSTOMER DRAWING FOR 1.00mm&1.50mm PITCH 2.00mmH CABLE SIDE WTB CONN
SCALE: N/A	MATERIAL: N/A	Q'TY N/A	DRAWING: Ruiju YOU	DRAWING NO.: 820-0000-0725
SHEET: 4/4	FINISH: N/A	④	 <b>Highstar</b> <b>Drapho ELECTRONICS TECHNOLOGY CO., LTD</b>	
REV.: Bx2				